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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	M32C/80
Core Size	16/32-Bit
Speed	32MHz
Connectivity	CANbus, I ² C, IEBus, SIO, UART/USART
Peripherals	DMA, WDT
Number of I/O	121
Program Memory Size	320KB (320K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 34x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LFQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m30855fwgp-u3

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1. Overview

The M32C/85 group (M32C/85, M32C/85T) microcomputer is a single-chip control unit that utilizes high-performance silicon gate CMOS technology with the M32C/80 series CPU core. The M32C/85 group (M32C/85, M32C/85T) is available in 144-pin and 100-pin plastic molded LQFP/QFP packages.

With a 16-Mbyte address space, this microcomputer combines advanced instruction manipulation capabilities to process complex instructions by less bytes and execute instructions at higher speed.

It includes a multiplier and DMAC adequate for office automation, communication devices and industrial equipments, and other high-speed processing applications.

1.1 Applications

Automobiles, audio, cameras, office equipment, communications equipment, portable equipment, etc.

1.4 Product Information

Table 1.3 lists the product information. Figure 1.2 shows the product numbering system.

Table 1.3 M32C/85 Group (1) (M32C/85)

As of July, 2005

Type Number	Package Type	ROM Capacity	RAM Capacity	Remarks
M30855FJGP	PLQP0144KA-A (144P6Q-A)	512K+4K	24K	Flash Memory
M30853FJGP	PLQP0100KB-A (100P6Q-A)			
M30853FJFP	PRQP0100JB-A (100P6S-A)			
M30855FHGP	PLQP0144KA-A (144P6Q-A)	384K+4K		
M30853FHGP	PLQP0100KB-A (100P6Q-A)			
M30853FHFP	PRQP0100JB-A (100P6S-A)			
M30855FWGP	PLQP0144KA-A (144P6Q-A)	320K+4K		
M30853FWGP	PLQP0100KB-A (100P6Q-A)			
M30853FWFP	PRQP0100JB-A (100P6S-A)			
M30855MW-XXXGP	PLQP0144KA-A (144P6Q-A)	320K		Mask ROM
M30853MW-XXXGP	PLQP0100KB-A (100P6Q-A)			
M30853MW-XXXFP	PRQP0100JB-A (100P6S-A)			

Table 1.3 M32C/85 Group (2) (T Version, M32C/85T)

As of July, 2005

Type Number	Package Type	ROM Capacity	RAM Capacity	Remarks
M30855FJTGP	PLQP0144KA-A (144P6Q-A)	512K+4K	24K	Flash Memory T Version (High-reliability 85°C Version)
M30853FJTGP	PLQP0100KB-A (100P6Q-A)			
M30855FHTGP	PLQP0144KA-A (144P6Q-A)	384K+4K		
M30853FHTGP	PLQP0100KB-A (100P6Q-A)			
M30855FWTGP	PLQP0144KA-A (144P6Q-A)	320K+4K		
M30853FWTGP	PLQP0100KB-A (100P6Q-A)			

1.5 Pin Assignments and Descriptions

Figures 1.3 to 1.5 show pin assignments (top view).

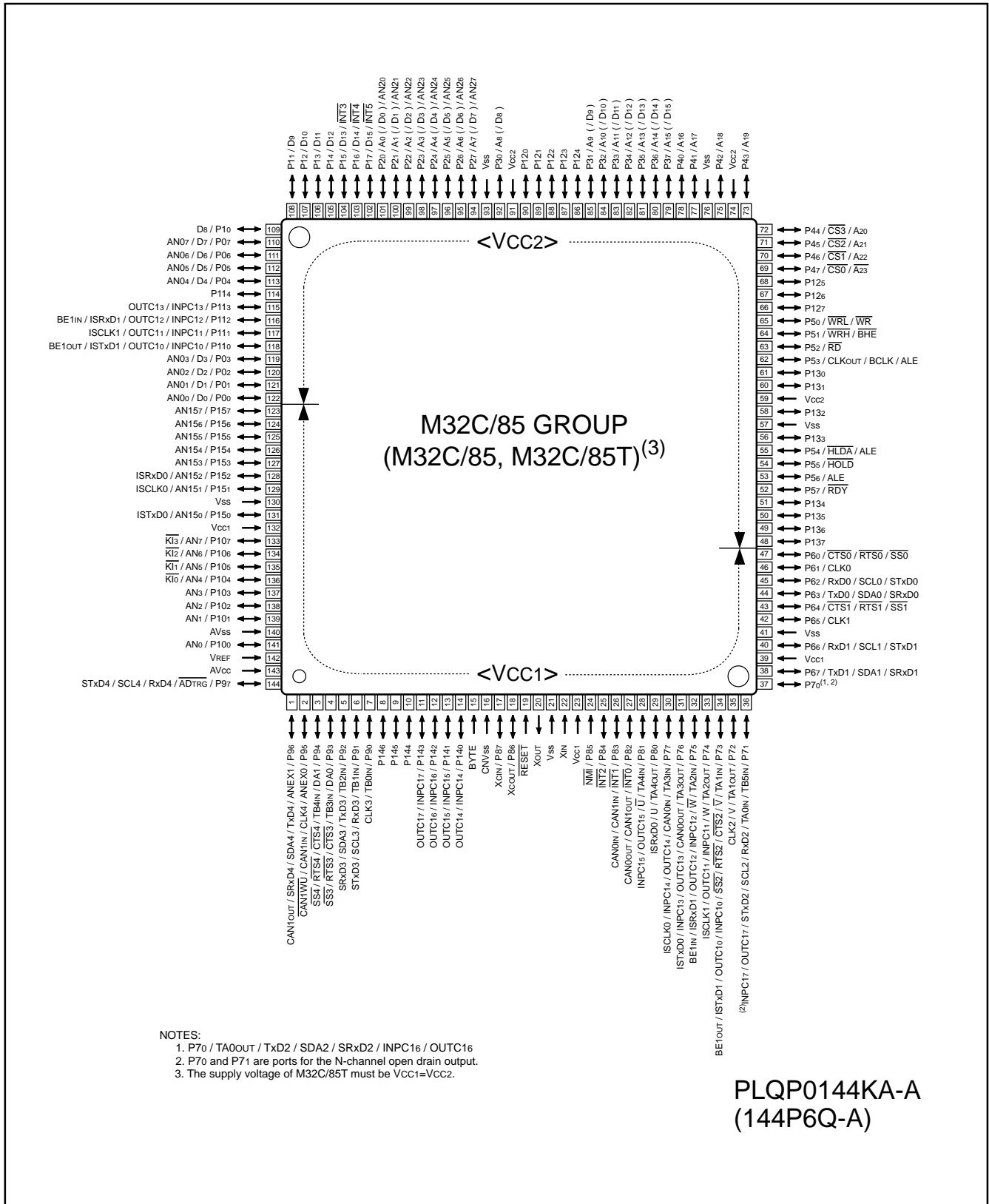


Figure 1.3 Pin Assignment for 144-Pin Package

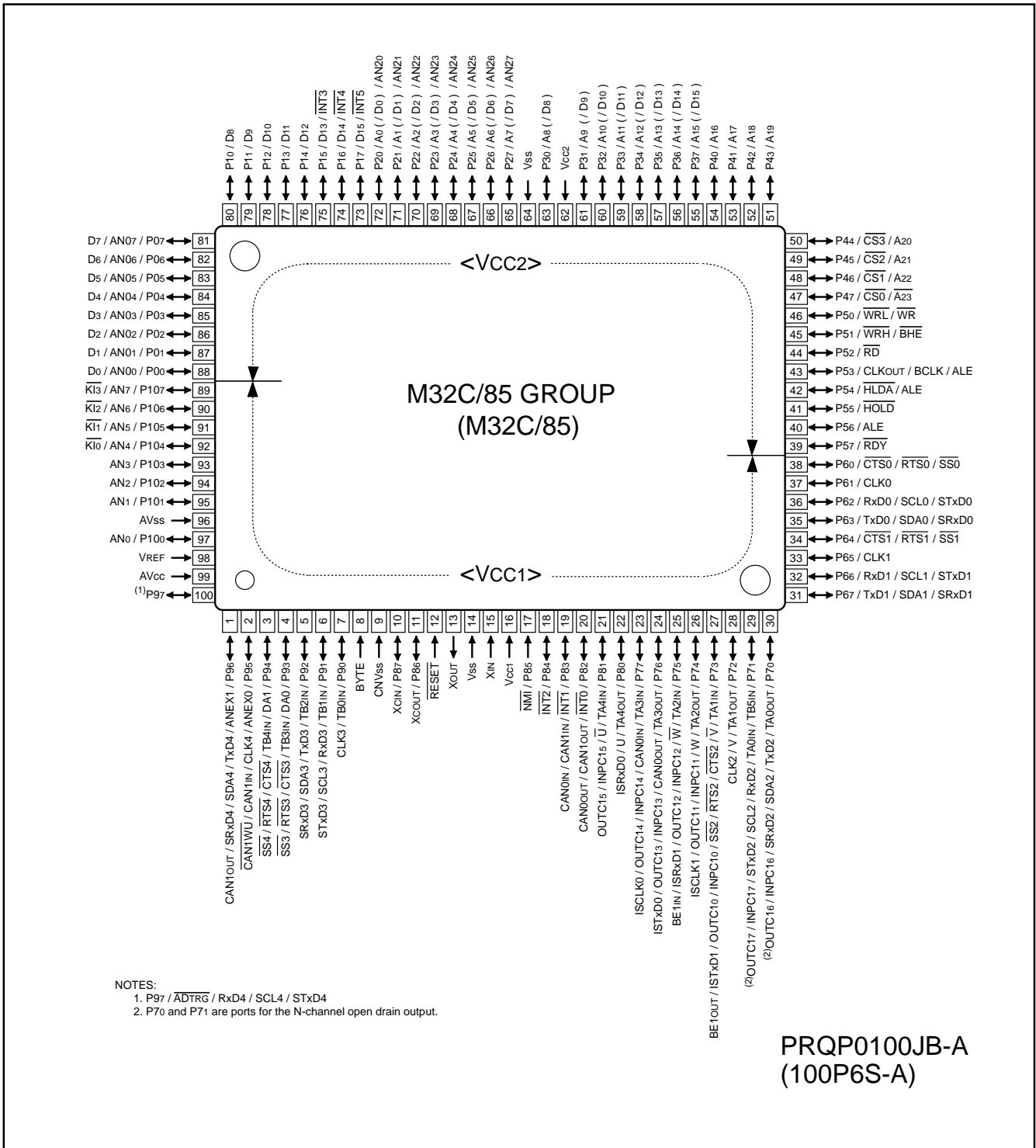


Figure 1.5 Pin Assignment for 100-Pin Package

Table 1.6 Pin Description (100-Pin and 144-Pin Packages) (Continued)

Classification	Symbol	I/O Type	Supply Voltage	Function
Main Clock Input	XIN	I	VCC1	I/O pins for the main clock oscillation circuit. Connect a ceramic resonator or crystal oscillator between XIN and XOUT. To apply external clock, apply it to XIN and leave XOUT open
Main Clock Output	XOUT	O	VCC1	
Sub Clock Input	XCIN	I	VCC1	I/O pins for the sub clock oscillation circuit. Connect a crystal oscillator between XCIN and XOUT. To apply external clock, apply it to XCIN and leave XOUT open
Sub Clock Output	XCOUT	O	VCC1	
BCLK Output ⁽¹⁾	BCLK	O	VCC2	Outputs BCLK signal
Clock Output	CLKOUT	O	VCC2	Outputs the clock having the same frequency as fc, f8 or f32
INT Interrupt Input	INT0 to INT2	I	VCC1	Input pins for the INT interrupt
	INT3 to INT5		VCC2	
NMI Interrupt Input	NMI	I	VCC1	Input pin for the NMI interrupt
Key Input Interrupt	KI0 to KI3	I	VCC1	Input pins for the key input interrupt
Timer A	TA0OUT to TA4OUT	I/O	VCC1	I/O pins for the timer A0 to A4 (TA0OUT is a pin for the N-channel open drain output.)
	TA0IN to TA4IN	I	VCC1	Input pins for the timer A0 to A4
Timer B	TB0IN to TB5IN	I	VCC1	Input pins for the timer B0 to B5
Three-phase Motor Control Timer Output	U, \bar{U} , V, \bar{V} , W, \bar{W}	O	VCC1	Output pins for the three-phase motor control timer
Serial I/O	CTS0 to CTS4	I	VCC1	Input pins for data transmission control
	RTS0 to RTS4	O	VCC1	Output pins for data reception control
	CLK0 to CLK4	I/O	VCC1	Inputs and outputs the transfer clock
	RxD0 to RxD4	I	VCC1	Inputs serial data
	TxD0 to TxD4	O	VCC1	Outputs serial data (TxD2 is a pin for the N-channel open drain output.)
I ² C Mode	SDA0 to SDA4	I/O	VCC1	Inputs and outputs serial data (SDA2 is a pin for the N-channel open drain output.)
	SCL0 to SCL4			Inputs and outputs the transfer clock (SCL2 is a pin for the N-channel open drain output.)
Serial I/O Special Function	STxD0 to STxD4	O	VCC1	Outputs serial data when slave mode is selected (STxD2 is a pin for the N-channel open drain output.)
	SRxD0 to SRxD4	I		Inputs serial data when slave mode is selected
	SS0 to SS4	I	VCC1	Input pins to control serial I/O special function

I : Input O : Output I/O : Input and output

NOTES:

1. Bus control pins in M32C/85T cannot be used.

Table 1.6 Pin Description (100-Pin and 144-Pin Packages) (Continued)

Classification	Symbol	I/O Type	Supply Voltage	Function
Reference Voltage Input	VREF	I	-	Applies reference voltage to the A/D converter and D/A converter
A/D Converter	AN0 to AN7 AN00 to AN07 AN20 to AN27	I	VCC1	Analog input pins for the A/D converter
	ADTRG	I	VCC1	Input pin for an external A/D trigger
	ANEX0	I/O	VCC1	Extended analog input pin for the A/D converter and output pin in external op-amp connection mode
	ANEX1	I	VCC1	Extended analog input pin for the A/D converter
D/A Converter	DA0, DA1	O	VCC1	Output pin for the D/A converter
Intelligent I/O	INPC10 to INPC13	I	VCC1/VCC2 ⁽¹⁾	Input pins for the time measurement function
	INPC14 to INPC17		VCC1	
	OUTC10 to OUTC13	O	VCC1/VCC2 ⁽¹⁾	Output pins for the waveform generating function (OUTC16 and OUTC17 assigned to P70 and P71 are pins for the N-channel open drain output.)
	OUTC14 to OUTC17		VCC1	
	ISCLK0	I/O	VCC1	Inputs and outputs the clock for the intelligent I/O communication function
	ISCLK1		VCC1/VCC2 ⁽¹⁾	
	ISRXD0	I	VCC1	Inputs data for the intelligent I/O communication function
	ISRXD1		VCC1/VCC2 ⁽¹⁾	
	ISTXD0	O	VCC1	Outputs data for the intelligent I/O communication function
	ISTXD1		VCC1/VCC2 ⁽¹⁾	
	BE1IN	I	VCC1/VCC2 ⁽¹⁾	Inputs data for the intelligent I/O communication function
	BE1OUT	O	VCC1/VCC2 ⁽¹⁾	Outputs data for the intelligent I/O communication function
CAN	CAN0IN	I	VCC1	Input pin for the CAN communication function
	CAN1IN			
	CAN0OUT	O		Output pin for the CAN communication function
	CAN1OUT			
	CAN1WU	I		Input pin for the CAN1 wake-up interrupt
I/O Ports	P00 to P07 P10 to P17 P20 to P27 P30 to P37 P40 to P47 P50 to P57	I/O	VCC2	I/O ports for CMOS. Each port can be programmed for input or output under the control of the direction register. An input port can be set, by program, for a pull-up resistor available or for no pull-up resistor available in 4-bit units
	P60 to P67 P70 to P77 P90 to P97 P100 to P107	I/O	VCC1	I/O ports having equivalent functions to P0 (P70 and P71 are ports for the N-channel open drain output.)
	P80 to P84 P86, P87	I/O	VCC1	I/O ports having equivalent functions to P0
	Input Port	P85	I	VCC1

I : Input O : Output I/O : Input and output

NOTES:

1. VCC2 is not available in the 100-pin package. VCC1 only available.

Address	Register	Symbol	Value after RESET
0060 ₁₆			
0061 ₁₆			
0062 ₁₆			
0063 ₁₆			
0064 ₁₆			
0065 ₁₆			
0066 ₁₆			
0067 ₁₆			
0068 ₁₆	DMA0 Interrupt Control Register	DM0IC	XXXX X0002
0069 ₁₆	Timer B5 Interrupt Control Register	TB5IC	XXXX X0002
006A ₁₆	DMA2 Interrupt Control Register	DM2IC	XXXX X0002
006B ₁₆	UART2 Receive /ACK Interrupt Control Register	S2RIC	XXXX X0002
006C ₁₆	Timer A0 Interrupt Control Register	TA0IC	XXXX X0002
006D ₁₆	UART3 Receive /ACK Interrupt Control Register	S3RIC	XXXX X0002
006E ₁₆	Timer A2 Interrupt Control Register	TA2IC	XXXX X0002
006F ₁₆	UART4 Receive /ACK Interrupt Control Register	S4RIC	XXXX X0002
0070 ₁₆	Timer A4 Interrupt Control Register	TA4IC	XXXX X0002
0071 ₁₆	UART0/UART3 Bus Conflict Detect Interrupt Control Register	BCN0IC/BCN3IC	XXXX X0002
0072 ₁₆	UART0 Receive/ACK Interrupt Control Register	S0RIC	XXXX X0002
0073 ₁₆	A/D0 Conversion Interrupt Control Register	AD0IC	XXXX X0002
0074 ₁₆	UART1 Receive/ACK Interrupt Control Register	S1RIC	XXXX X0002
0075 ₁₆	Intelligent I/O Interrupt Control Register 0/ CAN Interrupt 3 Control Register	IIO0IC/ CAN3IC	XXXX X0002
0076 ₁₆	Timer B1 Interrupt Control Register	TB1IC	XXXX X0002
0077 ₁₆	Intelligent I/O Interrupt Control Register 2	IIO2IC	XXXX X0002
0078 ₁₆	Timer B3 Interrupt Control Register	TB3IC	XXXX X0002
0079 ₁₆	Intelligent I/O Interrupt Control Register 4	IIO4IC	XXXX X0002
007A ₁₆	INT5 Interrupt Control Register	INT5IC	XX00 X0002
007B ₁₆			
007C ₁₆	INT3 Interrupt Control Register	INT3IC	XX00 X0002
007D ₁₆	Intelligent I/O Interrupt Control Register 8	IIO8IC	XXXX X0002
007E ₁₆	INT1 Interrupt Control Register	INT1IC	XX00 X0002
007F ₁₆	Intelligent I/O Interrupt Control Register 10/ CAN Interrupt 1 Control Register	IIO10IC/ CAN1IC	XXXX X0002
0080 ₁₆			
0081 ₁₆	CAN Interrupt 2 Control Register	CAN2IC	XXXX X0002
0082 ₁₆			
0083 ₁₆			
0084 ₁₆			
0085 ₁₆			
0086 ₁₆			
0087 ₁₆			
0088 ₁₆	DMA1 Interrupt Control Register	DM1IC	XXXX X0002
0089 ₁₆	UART2 Transmit /NACK Interrupt Control Register	S2TIC	XXXX X0002
008A ₁₆	DMA3 Interrupt Control Register	DM3IC	XXXX X0002
008B ₁₆	UART3 Transmit /NACK Interrupt Control Register	S3TIC	XXXX X0002
008C ₁₆	Timer A1 Interrupt Control Register	TA1IC	XXXX X0002
008D ₁₆	UART4 Transmit /NACK Interrupt Control Register	S4TIC	XXXX X0002
008E ₁₆	Timer A3 Interrupt Control Register	TA3IC	XXXX X0002
008F ₁₆	UART2 Bus Conflict Detect Interrupt Control Register	BCN2IC	XXXX X0002

X: Indeterminate

Blank spaces are reserved. No access is allowed.

Address	Register	Symbol	Value after RESET
0210 ₁₆	CAN0 Slot Interrupt Mask Register	C0SIMKR	00 ₁₆ ⁽²⁾
0211 ₁₆			00 ₁₆ ⁽²⁾
0212 ₁₆			
0213 ₁₆			
0214 ₁₆	CAN0 Error Interrupt Mask Register	C0EIMKR	XXXX X000 ₂ ⁽²⁾
0215 ₁₆	CAN0 Error Interrupt Status Register	C0EISTR	XXXX X000 ₂ ⁽²⁾
0216 ₁₆	CAN0 Error Cause Register	C0EFR	00 ₁₆ ⁽²⁾
0217 ₁₆	CAN0 Baud Rate Prescaler	C0BRP	0000 0001 ₂ ⁽²⁾
0218 ₁₆			
0219 ₁₆	CAN0 Mode Register	C0MDR	XXXX XX00 ₂ ⁽²⁾
021A ₁₆			
021B ₁₆			
021C ₁₆			
021D ₁₆			
021E ₁₆			
021F ₁₆			
0220 ₁₆	CAN0 Single Shot Control Register	C0SSCTLR	00 ₁₆ ⁽²⁾
0221 ₁₆			00 ₁₆ ⁽²⁾
0222 ₁₆			
0223 ₁₆			
0224 ₁₆	CAN0 Single Shot Status Register	C0SSSTR	00 ₁₆ ⁽²⁾
0225 ₁₆			00 ₁₆ ⁽²⁾
0226 ₁₆			
0227 ₁₆			
0228 ₁₆	CAN0 Global Mask Register Standard ID0	C0GMR0	XXX0 0000 ₂ ⁽²⁾
0229 ₁₆	CAN0 Global Mask Register Standard ID1	C0GMR1	XX00 0000 ₂ ⁽²⁾
022A ₁₆	CAN0 Global Mask Register Extended ID0	C0GMR2	XXXX 0000 ₂ ⁽²⁾
022B ₁₆	CAN0 Global Mask Register Extended ID1	C0GMR3	00 ₁₆ ⁽²⁾
022C ₁₆	CAN0 Global Mask Register Extended ID2	C0GMR4	XX00 0000 ₂ ⁽²⁾
022D ₁₆			
022E ₁₆			
022F ₁₆			
0230 ₁₆	CAN0 Message Slot 0 Control Register / CAN0 Local Mask Register A Standard ID0	C0MCTL0/ C0LMAR0	0000 0000 ₂ ⁽²⁾ XXX0 0000 ₂ ⁽²⁾
0231 ₁₆	CAN0 Message Slot 1 Control Register / CAN0 Local Mask Register A Standard ID1	C0MCTL1/ C0LMAR1	0000 0000 ₂ ⁽²⁾ XX00 0000 ₂ ⁽²⁾
0232 ₁₆	CAN0 Message Slot 2 Control Register / CAN0 Local Mask Register A Extended ID0	C0MCTL2/ C0LMAR2	0000 0000 ₂ ⁽²⁾ XXXX 0000 ₂ ⁽²⁾
0233 ₁₆	CAN0 Message Slot 3 Control Register / CAN0 local Mask Register A Extended ID1	C0MCTL3/ C0LMAR3	00 ₁₆ ⁽²⁾ 00 ₁₆ ⁽²⁾
0234 ₁₆	CAN0 Message Slot 4 Control Register / CAN0 Local Mask Register A Extended ID2	C0MCTL4/ C0LMAR4	0000 0000 ₂ ⁽²⁾ XX00 0000 ₂ ⁽²⁾
0235 ₁₆	CAN0 Message Slot 5 Control Register	C0MCTL5	00 ₁₆ ⁽²⁾
0236 ₁₆	CAN0 Message Slot 6 Control Register	C0MCTL6	00 ₁₆ ⁽²⁾
0237 ₁₆	CAN0 Message Slot 7 Control Register	C0MCTL7	00 ₁₆ ⁽²⁾
0238 ₁₆	CAN0 Message Slot 8 Control Register / CAN0 Local Mask Register B Standard ID0	C0MCTL8/ C0LMBR0	0000 0000 ₂ ⁽²⁾ XXX0 0000 ₂ ⁽²⁾
0239 ₁₆	CAN0 Message Slot 9 Control Register / CAN0 Local Mask Register B Standard ID1	C0MCTL9/ C0LMBR1	0000 0000 ₂ ⁽²⁾ XX00 0000 ₂ ⁽²⁾

(Note 1)

X: Indeterminate

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NOTES:

1. The BANKSEL bit in the C0CTLR1 register switches functions for addresses 0220₁₆ to 023F₁₆.
2. Values are obtained by setting the SLEEP bit in the C0SLPR register to "1" (sleep mode exited) after reset and applying the clock to the CAN module.

Address	Register	Symbol	Value after RESET
0290 ₁₆	CAN1 Slot Interrupt Mask Register	C1SIMKR	00 ₁₆
0291 ₁₆			00 ₁₆
0292 ₁₆			
0293 ₁₆			
0294 ₁₆	CAN1 Error Interrupt Mask Register	C1EIMKR	XXXX X000 ₂ ⁽²⁾
0295 ₁₆	CAN1 Error Interrupt Status Register	C1EISTR	XXXX X000 ₂ ⁽²⁾
0296 ₁₆	CAN1 Error Factor Register	C1EFR	00 ₁₆ ⁽²⁾
0297 ₁₆	CAN1 Baud Rate Prescaler	C1BRP	0000 0001 ₂ ⁽²⁾
0298 ₁₆			
0299 ₁₆	CAN1 Mode Register	C1MDR	XXXX XX00 ₂ ⁽²⁾
029A ₁₆			
029B ₁₆			
029C ₁₆			
029D ₁₆			
029E ₁₆			
029F ₁₆			
02A0 ₁₆	CAN1 Single Shot Control Register	C1SSCTLR	00 ₁₆ ⁽²⁾
02A1 ₁₆			00 ₁₆ ⁽²⁾
02A2 ₁₆			
02A3 ₁₆			
02A4 ₁₆	CAN1 Single Shot Status Register	C1SSSTR	00 ₁₆ ⁽²⁾
02A5 ₁₆			00 ₁₆ ⁽²⁾
02A6 ₁₆			
02A7 ₁₆			
02A8 ₁₆	CAN1 Global Mask Register Standard ID0	C1GMR0	XXX0 0000 ₂ ⁽²⁾
02A9 ₁₆	CAN1 Global Mask Register Standard ID1	C1GMR1	XX00 0000 ₂ ⁽²⁾
02AA ₁₆	CAN1 Global Mask Register Extended ID0	C1GMR2	XXXX 0000 ₂ ⁽²⁾
02AB ₁₆	CAN1 Global Mask Register Extended ID1	C1GMR3	00 ₁₆ ⁽²⁾
02AC ₁₆	CAN1 Global Mask Register Extended ID2	C1GMR4	XX00 0000 ₂ ⁽²⁾
02AD ₁₆			
02AE ₁₆			
02AF ₁₆			
02B0 ₁₆	CAN1 Message Slot 0 Control Register / CAN1 Local Mask Register A Standard ID0	C1MCTL0/ C1LMAR0	0000 0000 ₂ ⁽²⁾ XXX0 0000 ₂ ⁽²⁾
02B1 ₁₆	CAN1 Message Slot 1 Control Register / CAN1 Local Mask Register A Standard ID1	C1MCTL1/ C1LMAR1	0000 0000 ₂ ⁽²⁾ XX00 0000 ₂ ⁽²⁾
02B2 ₁₆	CAN1 Message Slot 2 Control Register / CAN1 Local Mask Register A Extended ID0	C1MCTL2/ C1LMAR2	0000 0000 ₂ ⁽²⁾ XXXX 0000 ₂ ⁽²⁾
02B3 ₁₆	CAN1 Message Slot 3 Control Register / CAN1 Local Mask Register A Extended ID1	C1MCTL3/ C1LMAR3	00 ₁₆ ⁽²⁾ 00 ₁₆ ⁽²⁾
02B4 ₁₆	CAN1 Message Slot 4 Control Register / CAN1 Local Mask Register A Extended ID2	C1MCTL4/ C1LMAR4	0000 0000 ₂ ⁽²⁾ XX00 0000 ₂ ⁽²⁾
02B5 ₁₆	CAN1 Message Slot 5 Control Register	C1MCTL5	00 ₁₆ ⁽²⁾
02B6 ₁₆	CAN1 Message Slot 6 Control Register	C1MCTL6	00 ₁₆ ⁽²⁾
02B7 ₁₆	CAN1 Message Slot 7 Control Register	C1MCTL7	00 ₁₆ ⁽²⁾
02B8 ₁₆	CAN1 Message Slot 8 Control Register / CAN1 Local Mask Register B Standard ID0	C1MCTL8/ C1LMBR0	0000 0000 ₂ ⁽²⁾ XXX0 0000 ₂ ⁽²⁾
02B9 ₁₆	CAN1 Message Slot 9 Control Register / CAN1 Local Mask Register B Standard ID1	C1MCTL9/ C1LMBR1	0000 0000 ₂ ⁽²⁾ XX00 0000 ₂ ⁽²⁾

(Note 1)

X: Indeterminate

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NOTES:

1. The BANKSEL bit in the C1CTLR1 register switches functions for addresses 02A0₁₆ to 02BF₁₆.
2. Values are obtained by setting the SLEEP bit in the C1SLPR register to "1" (sleep mode exited) after reset and applying the clock to the CAN module.

Address	Register	Symbol	Value after RESET
0310 ₁₆ 0311 ₁₆	Timer B3 Register	TB3	XX ₁₆ XX ₁₆
0312 ₁₆ 0313 ₁₆	Timer B4 Register	TB4	XX ₁₆ XX ₁₆
0314 ₁₆ 0315 ₁₆	Timer B5 Register	TB5	XX ₁₆ XX ₁₆
0316 ₁₆			
0317 ₁₆			
0318 ₁₆			
0319 ₁₆			
031A ₁₆			
031B ₁₆	Timer B3 Mode Register	TB3MR	00XX 0000 ₂
031C ₁₆	Timer B4 Mode Register	TB4MR	00XX 0000 ₂
031D ₁₆	Timer B5 Mode Register	TB5MR	00XX 0000 ₂
031E ₁₆			
031F ₁₆	External Interrupt Request Source Select Register	IFSR	00 ₁₆
0320 ₁₆			
0321 ₁₆			
0322 ₁₆			
0323 ₁₆			
0324 ₁₆	UART3 Special Mode Register 4	U3SMR4	00 ₁₆
0325 ₁₆	UART3 Special Mode Register 3	U3SMR3	00 ₁₆
0326 ₁₆	UART3 Special Mode Register 2	U3SMR2	00 ₁₆
0327 ₁₆	UART3 Special Mode Register	U3SMR	00 ₁₆
0328 ₁₆	UART3 Transmit/Receive Mode Register	U3MR	00 ₁₆
0329 ₁₆	UART3 Bit Rate Register	U3BRG	XX ₁₆
032A ₁₆ 032B ₁₆	UART3 Transmit Buffer Register	U3TB	XX ₁₆ XX ₁₆
032C ₁₆	UART3 Transmit/Receive Control Register 0	U3C0	0000 1000 ₂
032D ₁₆	UART3 Transmit/Receive Control Register 1	U3C1	0000 0010 ₂
032E ₁₆ 032F ₁₆	UART3 Receive Buffer Register	U3RB	XX ₁₆ XX ₁₆
0330 ₁₆			
0331 ₁₆			
0332 ₁₆			
0333 ₁₆			
0334 ₁₆	UART2 Special Mode Register 4	U2SMR4	00 ₁₆
0335 ₁₆	UART2 Special Mode Register 3	U2SMR3	00 ₁₆
0336 ₁₆	UART2 Special Mode Register 2	U2SMR2	00 ₁₆
0337 ₁₆	UART2 Special Mode Register	U2SMR	00 ₁₆
0338 ₁₆	UART2 Transmit/Receive Mode Register	U2MR	00 ₁₆
0339 ₁₆	UART2 Bit Rate Register	U2BRG	XX ₁₆
033A ₁₆ 033B ₁₆	UART2 Transmit Buffer Register	U2TB	XX ₁₆ XX ₁₆
033C ₁₆	UART2 Transmit/Receive Control Register 0	U2C0	0000 1000 ₂
033D ₁₆	UART2 Transmit/Receive Control Register 1	U2C1	0000 0010 ₂
033E ₁₆ 033F ₁₆	UART2 Receive Buffer Register	U2RB	XX ₁₆ XX ₁₆

X: Indeterminate

Blank spaces are reserved. No access is allowed.

<100-pin package>

Address	Register	Symbol	Value after RESET
03D0 ₁₆			
03D1 ₁₆			
03D2 ₁₆	Set default value to "FF ₁₆ "		
03D3 ₁₆	Set default value to "FF ₁₆ "		
03D4 ₁₆			
03D5 ₁₆			
03D6 ₁₆			
03D7 ₁₆			
03D8 ₁₆			
03D9 ₁₆			
03DA ₁₆	Pull-Up Control Register 2	PUR2	00 ₁₆
03DB ₁₆	Pull-Up Control Register 3	PUR3	00 ₁₆
03DC ₁₆	Set default value to "00 ₁₆ "		
03DD ₁₆			
03DE ₁₆			
03DF ₁₆			
03E0 ₁₆	Port P0 Register	P0	XX ₁₆
03E1 ₁₆	Port P1 Register	P1	XX ₁₆
03E2 ₁₆	Port P0 Direction Register	PD0	00 ₁₆
03E3 ₁₆	Port P1 Direction Register	PD1	00 ₁₆
03E4 ₁₆	Port P2 Register	P2	XX ₁₆
03E5 ₁₆	Port P3 Register	P3	XX ₁₆
03E6 ₁₆	Port P2 Direction Register	PD2	00 ₁₆
03E7 ₁₆	Port P3 Direction Register	PD3	00 ₁₆
03E8 ₁₆	Port P4 Register	P4	XX ₁₆
03E9 ₁₆	Port P5 Register	P5	XX ₁₆
03EA ₁₆	Port P4 Direction Register	PD4	00 ₁₆
03EB ₁₆	Port P5 Direction Register	PD5	00 ₁₆
03EC ₁₆			
03ED ₁₆			
03EE ₁₆			
03EF ₁₆			
03F0 ₁₆	Pull-up Control Register 0	PUR0	00 ₁₆
03F1 ₁₆	Pull-up Control Register 1	PUR1	XXXX 0000 ₂
03F2 ₁₆			
03F3 ₁₆			
03F4 ₁₆			
03F5 ₁₆			
03F6 ₁₆			
03F7 ₁₆			
03F8 ₁₆			
03F9 ₁₆			
03FA ₁₆			
03FB ₁₆			
03FC ₁₆			
03FD ₁₆			
03FE ₁₆			
03FF ₁₆	Port Control Register	PCR	XXXX XXX0 ₂

X: Indeterminate

Blank spaces are reserved. No access is allowed.

Table 5.2 Recommended Operating Conditions (Continued)
(V_{CC1}=V_{CC2}=3.0V to 5.5V at Topr=-20 to 85°C unless otherwise specified)

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
f(BCLK)	CPU Clock Frequency	V _{CC1} =4.2 to 5.5V	0		32	MHz
		V _{CC1} =3.0 to 5.5V	0		24	MHz
f(XIN)	Main Clock Input Frequency	V _{CC1} =4.2 to 5.5V	0		32	MHz
		V _{CC1} =3.0 to 5.5V	0		24	MHz
f(XCIN)	Sub Clock Frequency		32.768	50	kHz	
f(Ring)	On-chip Oscillator Frequency (V _{CC1} =V _{CC2} =5.0V, Topr=25° C)		0.5	1	2	MHz
f(PLL)	PLL Clock Frequency	V _{CC1} =4.2 to 5.5V	10		32	MHz
		V _{CC1} =3.0 to 5.5V	10		24	MHz
t _{SU(PLL)}	Wait Time to Stabilize PLL Frequency Synthesizer	V _{CC1} =5.0V			5	ms
		V _{CC1} =3.3V			10	ms

$$V_{CC1}=V_{CC2}=5V$$

Timing Requirements

($V_{CC1}=V_{CC2}=4.2$ to $5.5V$, $V_{SS}=0V$ at $T_{opr}=-20$ to $85^{\circ}C$ unless otherwise specified)

Table 5.9 External Clock Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t_c	External Clock Input Cycle Time	31.25		ns
$t_{w(H)}$	External Clock Input High ("H") Width	13.75		ns
$t_{w(L)}$	External Clock Input Low ("L") Width	13.75		ns
t_r	External Clock Rise Time		5	ns
t_f	External Clock Fall Time		5	ns

Table 5.10 Memory Expansion Mode and Microprocessor Mode

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{ac1(RD-DB)}$	Data Input Access Time (RD standard)		(Note 1)	ns
$t_{ac1(AD-DB)}$	Data Input Access Time (AD standard, CS standard)		(Note 1)	ns
$t_{ac2(RD-DB)}$	Data Input Access Time (RD standard, when accessing a space with the multiplexed bus)		(Note 1)	ns
$t_{ac2(AD-DB)}$	Data Input Access Time (AD standard, when accessing a space with the multiplexed bus)		(Note 1)	ns
$t_{su(DB-BCLK)}$	Data Input Setup Time	26		ns
$t_{su(RDY-BCLK)}$	\overline{RDY} Input Setup Time	26		ns
$t_{su(HOLD-BCLK)}$	\overline{HOLD} Input Setup Time	30		ns
$t_{h(RD-DB)}$	Data Input Hold Time	0		ns
$t_{h(BCLK-RDY)}$	\overline{RDY} Input Hold Time	0		ns
$t_{h(BCLK-HOLD)}$	\overline{HOLD} Input Hold Time	0		ns
$t_{d(BCLK-HLDA)}$	\overline{HLDA} Output Delay Time		25	ns

NOTES:

1. Values can be obtained from the following equations, according to BCLK frequency and external bus cycles. Insert a wait state or lower the operation frequency, $f_{(BCLK)}$, if the calculated value is negative.

$$t_{ac1(RD-DB)} = \frac{10^9 \times m}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}] \text{ (if external bus cycle is } a\phi + b\phi, m=(bx2)+1)$$

$$t_{ac1(AD-DB)} = \frac{10^9 \times n}{f_{(BCLK)}} - 35 \quad [\text{ns}] \text{ (if external bus cycle is } a\phi + b\phi, n=a+b)$$

$$t_{ac2(RD-DB)} = \frac{10^9 \times m}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}] \text{ (if external bus cycle is } a\phi + b\phi, m=(bx2)-1)$$

$$t_{ac2(AD-DB)} = \frac{10^9 \times p}{f_{(BCLK)} \times 2} - 35 \quad [\text{ns}] \text{ (if external bus cycle is } a\phi + b\phi, p=\{(a+b-1)x2\}+1)$$

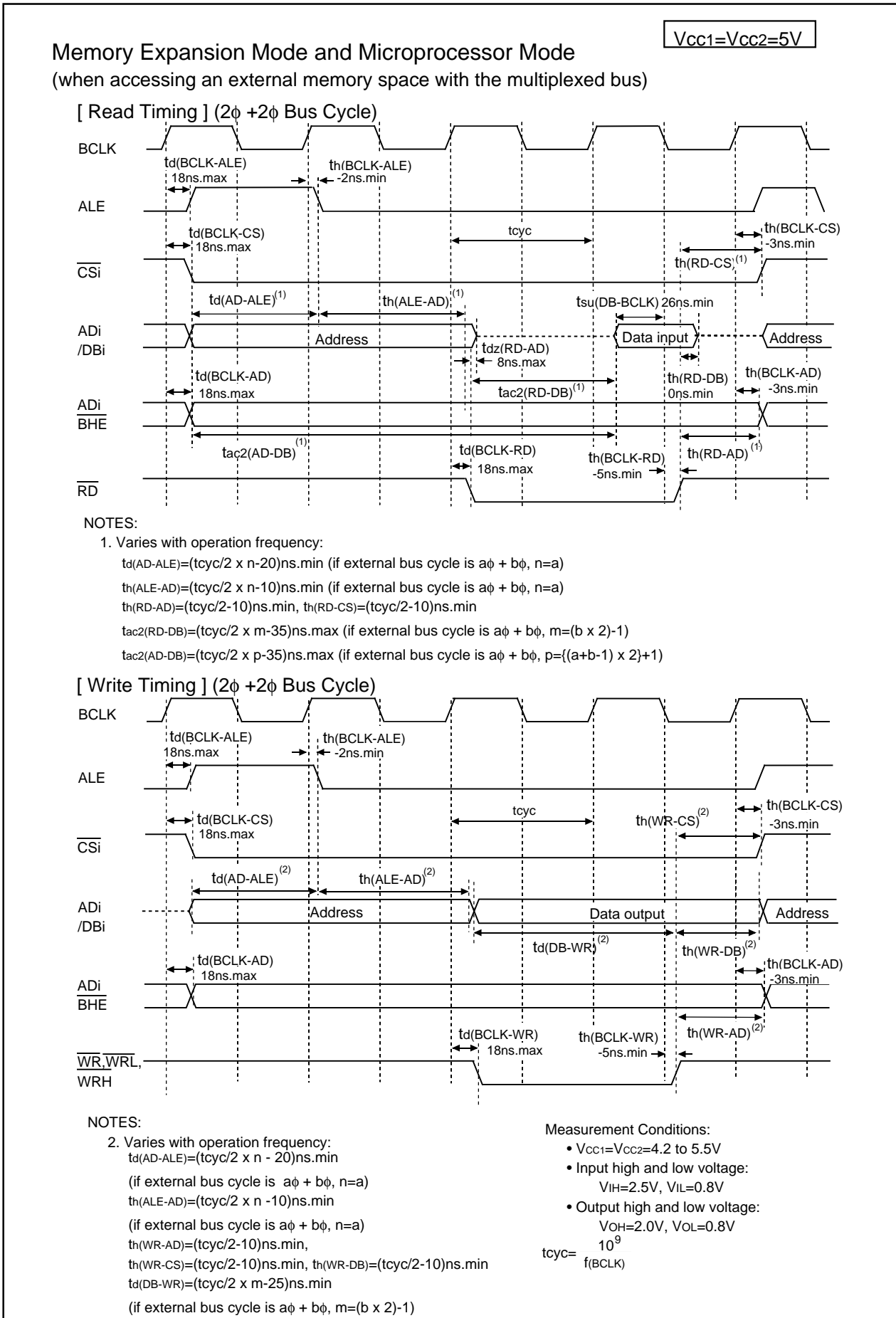


Figure 5.4 V_{CC1}=V_{CC2}=5V Timing Diagram (2)

$$V_{CC1}=V_{CC2}=3.3V$$

Table 5.24 Electrical Characteristics ($V_{CC1}=V_{CC2}=3.0$ to $3.6V$, $V_{SS}=0V$ at $T_{opr} = -20$ to $85^{\circ}C$, $f(BCLK)=24MHz$ unless otherwise specified)

Symbol	Parameter	Condition	Standard			Unit		
			Min.	Typ.	Max.			
V _{OH}	Output High ("H") Voltage	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P110-P114, P120-P127, P130-P137	I _{OH} =-1mA	V _{CC2} -0.6		V _{CC2}	V	
		P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P140-P146, P150-P157 ⁽¹⁾		V _{CC1} -0.6		V _{CC1}	V	
	X _{OUT}	I _{OH} =-0.1mA	2.7		V _{CC1}	V		
	X _{COUT}	High Power	No load applied		2.5		V	
		Low Power	No load applied		1.6		V	
V _{OL}	Output Low ("L") Voltage	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	I _{OL} =1mA			0.5	V	
		X _{OUT}	I _{OL} =0.1mA			0.5	V	
	X _{COUT}	High Power	No load applied		0		V	
		Low Power	No load applied		0		V	
	V _{T+} -V _{T-}	Hysteresis	HOLD, RDY, TA0IN-TA4IN, TB0IN-TB5IN, INT0-INT5, ADTRG, CTS0-CTS4, CLK0-CLK4, TA0OUT-TA4OUT, NMI, KI0-KI3, RxD0-RxD4, SCL0-SCL4, SDA0-SDA4		0.2		1.0	V
RESET				0.2		1.8	V	
I _{IH}	Input High ("H") Current	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾ , X _{IN} , RESET, CNV _{SS} , BYTE	V _I =3V			4.0	μA	
I _{IL}	Input Low ("L") Current	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾ , X _{IN} , RESET, CNV _{SS} , BYTE	V _I =0V			-4.0	μA	
R _{PULLUP}	Pull-up Resistance	P00-P07, P10-P17, P20-P27, P30-P37, P40-P47, P50-P57, P60-P67, P72-P77, P80-P84, P86, P87, P90-P97, P100-P107, P110-P114, P120-P127, P130-P137, P140-P146, P150-P157 ⁽¹⁾	V _I =0V	Flash Memory	66	120	500	kΩ
				Masked ROM	40	70	500	kΩ
R _{fXIN}	Feedback Resistance	X _{IN}				3.0	MΩ	
R _{fXCIN}	Feedback Resistance	X _{CIN}				20.0	MΩ	
V _{RAM}	RAM Standby Voltage	in stop mode			2.0		V	
I _{CC}	Power Supply Current	Measurement condition: In single-chip mode, output pins are left open and other pins are connected to V _{SS} .	f(BCLK)=24 MHz, Square wave, No division		22	35	mA	
			f(BCLK)=32 kHz, In wait mode, T _{opr} =25° C		10		μA	
			While clock stops, T _{opr} =25° C		0.8	5	μA	
			While clock stops, T _{opr} =85° C			50	μA	

NOTES:

1. P11 to P15 are provided in the 144-pin package only.

$V_{CC1}=V_{CC2}=3.3V$

Table 5.25 A/D Conversion Characteristics ($V_{CC1}=V_{CC2}=AV_{CC}=V_{REF}=3.0$ to $3.6V$, $V_{SS}=AV_{SS}=0V$ at $T_{opr} = -20$ to $85^{\circ}C$, $f(BCLK) = 24MHz$ unless otherwise specified)

Symbol	Parameter		Measurement Condition	Standard			Unit
				Min.	Typ.	Max.	
-	Resolution		$V_{REF}=V_{CC1}$			10	Bits
INL	Integral Nonlinearity Error	No S&H (8-bit)	$V_{CC1}=V_{CC2}=V_{REF}=3.3V$			± 2	LSB
DNL	Differential Nonlinearity Error	No S&H (8-bit)				± 1	LSB
-	Offset Error	No S&H (8-bit)				± 2	LSB
-	Gain Error	No S&H (8-bit)				± 2	LSB
RLADDER	Resistor Ladder		$V_{REF}=V_{CC1}$	8		40	k Ω
tCONV	8-bit Conversion Time ^(1, 2)			6.1			μs
VREF	Reference Voltage			3		V_{CC1}	V
VIA	Analog Input Voltage			0		V_{REF}	V

S&H: Sample and Hold

NOTES:

1. Divide $f(X_{IN})$, if exceeding 10 MHz, to keep ϕAD frequency at 10 MHz or less.
2. S&H not available.

Table 5.26 D/A Conversion Characteristics ($V_{CC1}=V_{CC2}=V_{REF}=3.0$ to $3.6V$, $V_{SS}=AV_{SS}=0V$ at $T_{opr} = -20$ to $85^{\circ}C$, $f(BCLK) = 24MHz$ unless otherwise specified)

Symbol	Parameter		Measurement Condition	Standard			Unit
				Min.	Typ.	Max.	
-	Resolution					8	Bits
-	Absolute Accuracy					1.0	%
tsu	Setup Time					3	μs
Ro	Output Resistance			4	10	20	k Ω
I _{VREF}	Reference Power Supply Input Current		(Note 1)			1.0	mA

NOTES:

1. Measurement results when using one D/A converter. The DA_i register (i=0, 1) of the D/A converter, not being used, is set to "00₁₆". The resistor ladder in the A/D converter is excluded.
I_{VREF} flows even if the VCUT bit in the AD0CON1 register is set to "0" (no V_{REF} connection).

Table 5.47 Flash Memory Version Electrical Characteristics
(VCC1=4.5 to 5.5V, 3.0 to 3.6V at Topr= 0 to 60°C unless otherwise specified)

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
-	Program and Erase Endurance ⁽²⁾		100			cycles
-	Word Program Time (VCC1=5.0V, Topr=25° C)			25	200	µs
-	Lock Bit Program Time			25	200	µs
-	Block Erase Time (VCC1=5.0V, Topr=25° C)	4-Kbyte Block		0.3	4	s
		8-Kbyte Block		0.3	4	s
		32-Kbyte Block		0.5	4	s
		64-Kbyte Block		0.8	4	s
-	All-Unlocked-Block Erase Time ⁽¹⁾				4 x <i>n</i>	s
tps	Wait Time to Stabilize Flash Memory Circuit				15	µs
-	Data Hold Time (Topr=-40 to 85 ° C)		10			years

NOTES:

1. *n* denotes the number of block to be erased.
2. Number of program-erase cycles per block.
 If Program and Erase Endurance is *n* cycle (*n*≠100), each block can be erased and programmed *n* cycles.
 For example, if a 4-Kbyte block A is erased after programming a word data 2,048 times, each to a different address, this counts as one program and erase endurance. Data can not be programmed to the same address more than once without erasing the block. (rewrite prohibited).

Table 5.48 Power Supply Timing

Symbol	Parameter	Measurement Condition	Standard			Unit
			Min.	Typ.	Max.	
td(P-R)	Wait Time to Stabilize Internal Supply Voltage when Power-on	VCC1=3.0 to 5.5V			2	ms

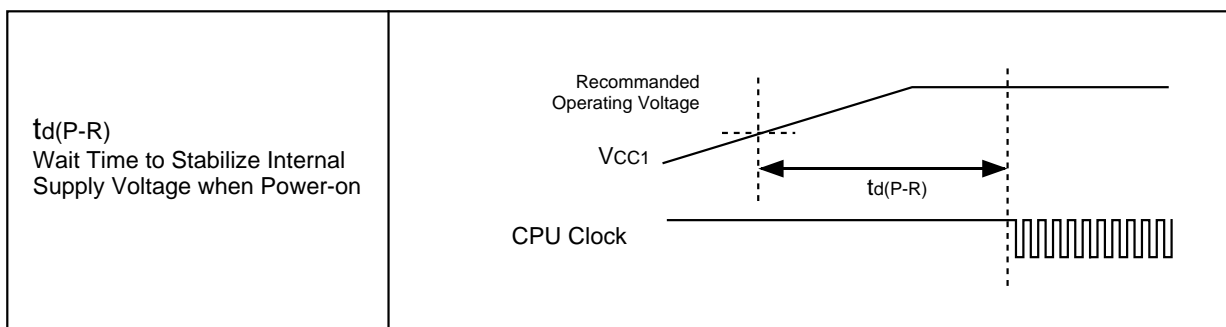


Figure 5.11 Power Supply Timing Diagram

REVISION HISTORY

M32C/85 Group (M32C/85, M32C/85T) Datasheet

Rev.	Date	Description	
		Page	Summary
		50	Electrical Characteristics • Table 5.3 Electrical Characteristics Maximum values for Power Supply Current modified
		52	• Table 5.6 Flash Memory Version Electrical Characteristics Note 1. 100-cycle Products (D3, D5, U3, U5) deleted; Note 4 modified
		63	• Table 5.7 Flash Memory Version Program and Erase Voltage and Read Operation Voltage Characteristics (at Topr=0 to 60°C) deleted • Table 5.22 Electrical Characteristics Maximum values for Power Supply Consumption modified and standard values when “Topr=85°C while clock is stopped” deleted
1.00	Jun.01, 2004	-	M32C/85T (High-reliability version) added
		All Pages	Words standardized: On-chip oscillator, A/D converter and D/A converter
		1	Overview • 1.1 Applications Automobiles added
		2, 3	• Table 1.1 and Table 1.2 M32C/85 Group (M32C/85, M32C/85T) Performance M32C/85T added; note 3 added
		4	• Figure 1.1 M32C/85 Group (M32C/85, M32C/85T) Block Diagram Note 3 added
		5	• 1.4 Product Information Description modified • Figure 1.2 ROM/RAM Capacity figure modified
		5, 6	• Table 1.3 M32C/85 Group M32C/85T added
		6	• Figure 1.3 Product Numbering System M32C/85T added
		7	• Figure 1.4 Pin Assignment for 144-Pin Package Note 3 added
		12	• Figure 1.6 Pin Assignment for 100-Pin Package Note 5 added
8 to 10	• Table 1.5 Pin Characteristics for 144-Pin Package Note 1 added		
13, 14	• Table 1.6 Pin Characteristics for 100-Pin Package Note 1 added		
15 to 18	• Table 1.7 Pin Description Notes added		
		22	Memory • Figure 3.1 Memory Map Tables of internal ROM/internal RAM modified; note 2 modified; notes 4 and 5 added
		23	SFR • Note 2 added
		24	• PWCR0 and PWCR1 registers deleted • “Values after RESET” of the masked ROM version added to the FMR0 register • Note 1 added
		46	Electrical Characteristics • Table 5.2 Recommended Operating Conditions f(ripple), Vp-p(ripple), VCC, SVCC and note 1 deleted
		47	• Table 5.3 Electrical Characteristics RPULLUP value for the masked ROM version added

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